

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wing-Hin Kao</td> <td>09/05/2013</td> </tr> <tr> <td>Jongsik Na</td> <td>09/05/2013</td> </tr> </tbody> </table>		Name	Execution Date	Wing-Hin Kao	09/05/2013	Jongsik Na	09/05/2013				
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Integrated Silicon Solution, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>1623 Buckeye Dr.</td> </tr> <tr> <td>City:</td> <td>Milpitas</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95035</td> </tr> </table>		Name:	Integrated Silicon Solution, Inc.	Street Address:	1623 Buckeye Dr.	City:	Milpitas	State/Country:	CALIFORNIA	Postal Code:	95035
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 4089732595 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 4089732585 Email: mgreen@ip-patent.com Correspondent Name: Van Pelt, Yi and James LLP Address Line 1: 10050 N. Foothill Blvd Address Line 2: Ste 200 Address Line 4: Cupertino, CALIFORNIA 95014</p>											
ATTORNEY DOCKET NUMBER:	ISSIP003										
NAME OF SUBMITTER:	Carmen C. Cook										
Signature:	/Carmen C Cook/										
Date:	09/27/2013										
Total Attachments: 1 source=ISSIP003 Executed Assignment#page1.tif											

CH \$40.00 13957251

ASSIGNMENT OF PATENT APPLICATION

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:


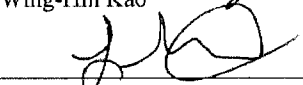
MEMORY DEVICE IMPLEMENTING REDUCED ECC OVERHEAD

for which I (we) have executed an application for a United States Letters Patent which was filed in the U.S. Patent and Trademark Office on August 1, 2013, and which bears the Application No. 13/957,251 (the "Application");

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we the undersigned inventor(s) hereby:

- 1) Sell, assign, and transfer to Integrated Silicon Solution, Inc., a corporation having a place of business at 1623 Buckeye Dr., Milpitas, CA 95035, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) (including foreign applications) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application and/or in any provisional application to which the above referenced application claims priority.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- | | | |
|----|---|-----------------------|
| 1) | Signature: <u></u> | Date: <u>9/5/2013</u> |
| | Typed Name: Wing-Hin Kao | |
| 2) | Signature: <u></u> | Date: <u>9/5/13</u> |
| | Typed Name: Jongsik Na | |